L Number	Hits	Search Text	DB	Time stamp
1	2539907	semiconductor die chip ic (integrated adj circuit) dice	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 06:20
2	687469	bump ball bga flipchip (flip adj chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 06:21
3	504975	disconnected disconnect disconnecting dummy inactive nonelectrical (non adj (electrical electrically connecting connected connect function functioning functioned))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 06:25
4	3988	(bump ball bga flipchip (flip adj chip)) with (disconnected disconnect disconnecting dummy inactive nonelectrical (non adj (electrical electrically connecting connected connect function functioning functioned)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 06:25
5	905	(semiconductor die chip ic (integrated adj circuit) dice) same ((bump ball bga flipchip (flip adj chip)) with (disconnected disconnect disconnecting dummy inactive nonelectrical (non adj (electrical electrically connecting connected connect function functioning functioned))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 06:26
6	206	(end corner peripheral) same ((semiconductor die chip ic (integrated adj circuit) dice) same ((bump ball bga flipchip (flip adj chip)) with (disconnected disconnect disconnecting dummy inactive nonelectrical (non adj (electrical electrically connecting connected connect function functioning functioned)))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/28 06:27

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